

AMENDMENTS TO THE ABSTRACT:

Please amend the Abstract originally appearing on page 39 of the application and as previously amended as follows:

ABSTRACT OF THE DISCLOSURE

One or more stabilizers are disposed on the surface of a semiconductor device component prior to bonding the same to a ~~higher-level~~ higher-level substrate. Upon assembly of the semiconductor device component face down upon a ~~higher-level~~ higher-level substrate and joining conductive structures between the contact pads of the semiconductor device component and corresponding contact pads of the ~~higher-level~~ higher-level substrate, the stabilizers at least partially stabilize the semiconductor device component on the ~~higher-level~~ higher-level substrate to maintain a substantially parallel relation therebetween. The stabilizers can also be positioned and configured to define a minimum, substantially uniform distance between the semiconductor device component and the ~~higher-level~~ higher-level substrate. The stabilizers may be preformed structures or fabricated on the surface of the semiconductor device component, such as by way of a stereolithographic method.